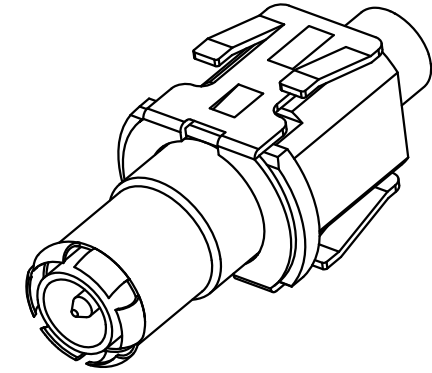
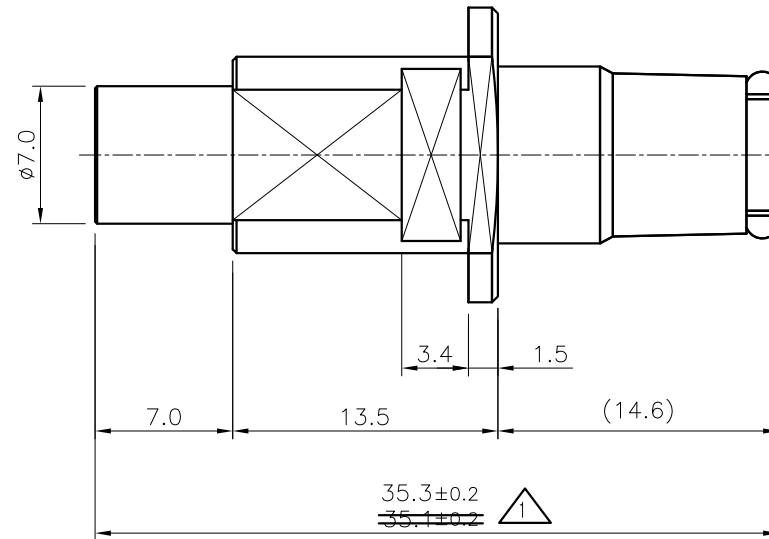
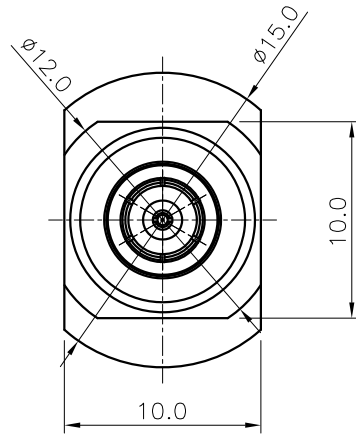
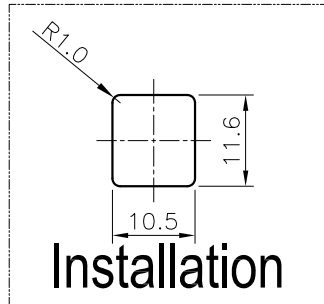


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	H.J.LEE	I.C.KIM	2016.03.30.
1	[설번No.201604-0014] 원가 절감으로 인한 TEFLON 변경, 현품에 맞게 치수 변경. PIN 위치 바늘 추가 및 BODY 내부 TEFLON 길이에 맞춰 변경	H.J.LEE	I.C.KIM	2016.04.29.

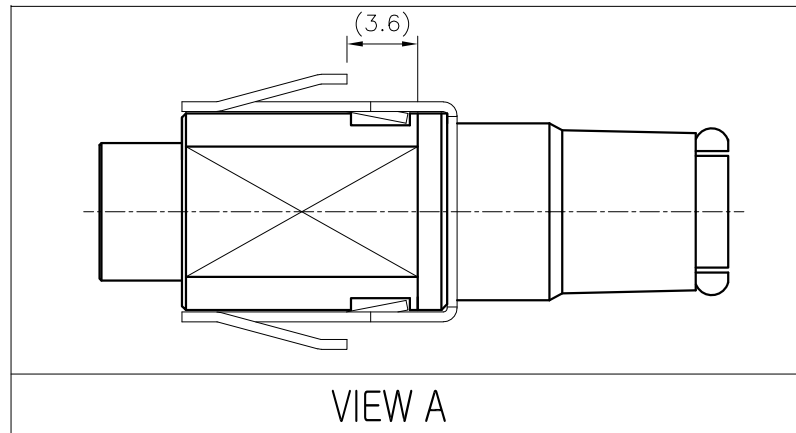


* 내전압 검사 할 것

* PCB 두께 권장 사양 : 3.2t ± 0.1mm



VIEW A



7	LOCK PANEL	1	SUS	Passivated	DSR00070-N/2
6	JACK	1	BeCu C17300	Nickel Plate	DJA00039-5/1
5	JACK	1	MBsBD C3604BD-F	Nickel Plate	DJA00225-5/1
4	INSULATOR	1	TEFLON		DAI02468-N/1
3	INSULATOR	1	TEFLON		DIN01960-N/1
2	CONTACT	1	BeCu C17300	Gold Plate	DAC03253-5/1
1	BODY	1	MBsBD C3604BD-F	Nickel Plate	DAD00310-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.1	DATE 2016. 04. 29.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle ±1°	APPROVED BY I.C.KIM			
MATERIAL _____		CHECKED BY		TITLE SMBL50 (J) TRU50 (P) ADAPTOR	
		DRAWN BY H.J.LEE			
FINISH _____		SCALE 2.5/1	UNIT mm		A4
		REVISION 1			SHEET 1 of 1